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## Ultra Low Power Buck PMIC

 Solar/Vibrations Energy HarvestingThe MB39C811 is the high efficient buck (Power Management) DC/DC converter IC which adopts the all-wave bridge rectifier using the low-dissipation and the comparator system. It achieves the energy harvest solution for the energy source of the high output impedance such as the piezoelectric transducer.
It is possible to select from eight preset output voltages and supply up to 100 mA of the output current.

## Features

- Quiescent current (No load, Output in regulation): $1.5 \mu \mathrm{~A}$
■ Quiescent current (VIN = 2.5V UVLO): 550nA
■ Integrated Low Loss Full-Wave Bridge Rectifier
■ VIN input voltage range: 2.6 V to 23 V
■ Preset output voltage: $1.5 \mathrm{~V}, 1.8 \mathrm{~V}, 2.5 \mathrm{~V}, 3.3 \mathrm{~V}, 3.6 \mathrm{~V}$, $4.1 \mathrm{~V}, 4.5 \mathrm{~V}, 5.0 \mathrm{~V}$

■ Output current: Up to 100 mA

- Protection functions

■ Shunt for input protection: VIN $\geq 21 \mathrm{~V}, \mathrm{Up}$ to 100 mA Pull-down
■ Over current limit
■ I/O power-good detection signal output

## Applications

■ Light energy harvesting
■ Piezoelectric energy harvesting

- Electro-Mechanical energy harvesting
- Wireless HVAC sensor

Stand-alone nano-power buck regulator

## Online Design Simulation Easy DesignSim

This product supports the web-based design simulation tool. It can easily select external components and can display useful information. Please access from the following URL.
http://cypress.transim.com/login.aspx

MB39C811

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## 1. Pin Assignments

Figure 1. Pin Assignments


## 2. Pin Descriptions

Table 1. Pin Descriptions.

| Pin No. | Pin <br> Name | I/O |  |
| :---: | :---: | :---: | :--- |
| 1 to 4 | N.C. | - | Non connection pins (Leavethese pins open) |
| 5 | VIN | - | DC power supply input pin |
| 6 | LX | O | DC/DC output pin |
| 7 | PGND | - | PGND pin |
| 8 | N.C. | - | Non connection pin (Leavethis pin open) |
| 9 | GND | - | GND pin |
| 10,11 | N.C. | - | Non connection pins (Leavethese pins open) |
| 12 | AC1_1 | I | Bridge Rectifier1 AC input pin 1 |
| 13 | DCOUT1 | O | Bridge Rectifier1 DC output pin |
| 14 | AC1_2 | I | Bridge Rectifier1 AC input pin 2 |
| 15 | DCGND1 | - | GND pin |
| 16 | DCGND2 | - | GND pin |
| 17 | AC2_2 | I | Bridge Rectifier2 AC input pin 2 |
| 18 | DCOUT2 | O | Bridge Rectifier2 DC output pin |
| 19 | AC2_1 | I | Bridge Rectifier2 AC input pin 1 |
| 20 | N.C. | - | Non connection pin (Leavethis pin open) |
| 21 | GND | - | GND pin |
| 22 | S2 | I | Output voltage select pin 2 |
| 23 | S1 | I | Output voltage select pin 1 |
| 24 | S0 | I | Output voltage select pin 0 |
| 25 | GND | - | GND pin |
| 26 | OPGOOD | O | Output power-good output pin |
| 27 | IPGOOD | O | Input power-good output pin |
| 28 | VOUT | I | Output voltage feedback pin |
| 29 | VB | O | Internal circuit power supply pin |
| 30 | GND | - | GND pin |
| 31 to 40 | N.C. | - | Non connection pins (Leavethese pins open) |
|  |  |  |  |
| 10 |  |  |  |

PERFORM

## 3. Block Diagram

Figure 2. Block Diagram


## 4. Absolute Maximum Ratings

Table 2. Absolute Maximum Ratings

| Parameter | Symbol | Condition | Rating |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | Min | Max |  |
| VIN pin input voltage | VVINMAX | VIN pin | -0.3 | +24 | V |
| VIN pin input slew rate | SRMAX | VIN pin (VIN $\geq 7 \mathrm{~V}$ ) | - | 0.25 | V/ms |
| VIN pin input current | IINMAX | VIN pin | - | 100 | mA |
| AC pin input voltage | VACMAX | AC1_1 pin, AC1_2 pin, AC2_1 pin, AC2_2 pin | -0.3 | +24 | V |
| AC pin input current | IPVMAX | AC1_1 pin, AC1_2 pin, <br> AC2_1 pin, AC2_2 pin | - | 50 | mA |
| LX pin input voltage | VLXMAX | LX pin | -0.3 | +24 | V |
| Input voltage | VVINPUTMAX | S0 pin, S1 pin, S2 pin | -0.3 | $\begin{aligned} & \text { VVB }+0.3 \\ & (\leq+7.0) \end{aligned}$ | V |
|  |  | VOUT pin | -0.3 | +7.0 | V |
| Power dissipation | PD | $\mathrm{Ta} \leq+25^{\circ} \mathrm{C}$ | - | 2500 | mW |
| Storage temperature | TSTG | - | -55 | +125 | ${ }^{\circ} \mathrm{C}$ |
| ESD voltage 1 | VESDH | Human Body Model ( $100 \mathrm{pF}, 5 \mathrm{k} \Omega$ ) | -900 | +2000 | V |
| ESD voltage 2 | VESDM | Machine Model (200pF, $0 \Omega$ ) | -150 | +150 | V |
| ESD voltage3 | VCDM | Charged Device Model | -1000 | +1000 | V |

Figure 3. Power Dissipation - Operating Ambient Temperature


## WARNING:

- Semiconductor devices may be permanently damaged by application of stress (including, without limitation, voltage, current or temperature) in excess of absolute maximum ratings. Do not exceed any of these ratings.


## 5. Recommended Operating Conditions

Table 3. Recommended operating conditions

| Parameter | Symbol | Condition | Value |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | Min | Typ | Max |  |
| VIN pin input voltage | VVIN | VIN pin | 2.6 | - | 23 | V |
| AC pin input voltage | VPV | AC1_1 pin, AC1_2 pin, AC2_1 pin, AC2_2 pin | - | - | 23 | V |
| Input voltage | VSI | S0 pin, S1 pin, S2 pin | 0 | - | VVB | V |
|  | VFB | VOUT pin | 0 | - | 5.5 | V |
| Operating ambient temperature | Ta | - | -40 | - | +85 | ${ }^{\circ} \mathrm{C}$ |

## WARNING:

- The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated under these conditions.
- Any use of semiconductor devices will be under their recommended operating condition.
- Operation under any conditions other than these conditions may adversely affect reliability of device and could result in device failure.
- No warranty is made with respect to any use, operating conditions or combinations not represented on this data sheet. If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.


## 6. Electrical Characteristics

### 6.1 DC Characteristics

Table 4. DC Characteristics
( $\mathrm{Ta}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}, \mathrm{VVIN}=7.0 \mathrm{~V}, \mathrm{~L} 1=22 \mu \mathrm{H}, \mathrm{C} 2=47 \mu \mathrm{~F}$ )

| Parameter | Symbol | Condition | Value |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | Min | Typ | Max |  |
| Quiescent current | IVIN | VVIN $=2.5 \mathrm{~V}$ (UVLO), $\mathrm{Ta}=+25^{\circ} \mathrm{C}$ | - | 550 | 775 | nA |
|  |  | $\mathrm{VVIN}=4.5 \mathrm{~V}$ (sleep mode), $\mathrm{Ta}=+25^{\circ} \mathrm{C}$ | - | 1.5 | 2.25 | $\mu \mathrm{A}$ |
|  |  | $\mathrm{VVIN}=18 \mathrm{~V}$ (sleep mode), $\mathrm{Ta}=+25^{\circ} \mathrm{C}$ | - | 1.9 | 2.85 | $\mu \mathrm{A}$ |
| Preset output voltage | VVOUT | $\mathrm{S} 2=\mathrm{L}, \mathrm{S} 1=\mathrm{L}, \mathrm{S} 0=\mathrm{L}, \mathrm{IOUT}=1 \mathrm{~mA}$ | 1.457 | 1.5 | 1.544 | V |
|  |  | $S 2=L, S 1=L, S 0=H, I O U T=1 \mathrm{~mA}$ | 1.748 | 1.8 | 1.852 | V |
|  |  | $\mathrm{S} 2=\mathrm{L}, \mathrm{S} 1=\mathrm{H}, \mathrm{S} 0=\mathrm{L}, \mathrm{IOUT}=1 \mathrm{~mA}$ | 2.428 | 2.5 | 2.573 | V |
|  |  | $\mathrm{S} 2=\mathrm{L}, \mathrm{S} 1=\mathrm{H}, \mathrm{S} 0=\mathrm{H}, \mathrm{IOUT}=1 \mathrm{~mA}$ | 3.214 | 3.3 | 3.386 | V |
|  |  | $\mathrm{S} 2=\mathrm{H}, \mathrm{S} 1=\mathrm{L}, \mathrm{S} 0=\mathrm{L}, \mathrm{IOUT}=1 \mathrm{~mA}$ | 3.506 | 3.6 | 3.694 | V |
|  |  | $\mathrm{S} 2=\mathrm{H}, \mathrm{S} 1=\mathrm{L}, \mathrm{SO}=\mathrm{H}, \mathrm{IOUT}=1 \mathrm{~mA}$ | 3.993 | 4.1 | 4.207 | V |
|  |  | $\mathrm{S} 2=\mathrm{H}, \mathrm{S} 1=\mathrm{H}, \mathrm{S} 0=\mathrm{L}, \mathrm{IOUT}=1 \mathrm{~mA}$ | 4.383 | 4.5 | 4.617 | V |
|  |  | $\mathrm{S} 2=\mathrm{H}, \mathrm{S} 1=\mathrm{H}, \mathrm{S} 0=\mathrm{H}, \mathrm{IOUT}=1 \mathrm{~mA}$ | 4.870 | 5.0 | 5.130 | V |
| Peak switching current | IPEAK | - | 200 | 250 | 400 | mA |
| Maximum Output current | IOUTMAX | $\mathrm{Ta}=+25^{\circ} \mathrm{C}$ | 100* | - | - | mA |
| UVLO release voltage (Input power-good detectionvoltage) | VUVLOH | $\mathrm{S} 2=\mathrm{L}, \mathrm{S} 1=\mathrm{L}, \mathrm{S} 0=\mathrm{L}$ | 3.8 | 4.0 | 4.2 | V |
|  |  | $S 2=L, S 1=L, S 0=H$ |  |  |  |  |
|  |  | S2 = L, S1 = H, S0 = L |  |  |  |  |
|  |  | S2 $=\mathrm{L}, \mathrm{S} 1=\mathrm{H}, \mathrm{S} 0=\mathrm{H}$ | 4.94 | 5.2 | 5.46 | V |
|  |  | $S 2=H, S 1=L, S 0=L$ |  |  |  |  |
|  |  | $S 2=H, S 1=L, S 0=H$ | 6.84 | 7.2 | 7.56 | V |
|  |  | S2 $=\mathrm{H}, \mathrm{S} 1=\mathrm{H}, \mathrm{S} 0=L$ |  |  |  |  |
|  |  | S2 $=\mathrm{H}, \mathrm{S} 1=\mathrm{H}, \mathrm{S} 0=H$ |  |  |  |  |
| UVLO detection voltage (Input power-good resetvoltage) | VUVLOL | $\mathrm{S} 2=\mathrm{L}, \mathrm{S} 1=\mathrm{L}, \mathrm{S} 0=\mathrm{L}$ | 2.6 | 2.8 | 3.0 | V |
|  |  | $S 2=L, S 1=L, S 0=H$ |  |  |  |  |
|  |  | $S 2=L, S 1=H, S 0=L$ |  |  |  |  |
|  |  | $S 2=L, S 1=H, S 0=H$ | 3.8 | 4.0 | 4.2 | V |
|  |  | $S 2=H, S 1=L, S 0=L$ |  |  |  |  |
|  |  | S2 $=\mathrm{H}, \mathrm{S} 1=\mathrm{L}, \mathrm{S} 0=H$ | 5.7 | 6.0 | 6.3 | V |
|  |  | S2 $=\mathrm{H}, \mathrm{S} 1=\mathrm{H}, \mathrm{S} 0=L$ |  |  |  |  |
|  |  | S2 $=\mathrm{H}, \mathrm{S} 1=\mathrm{H}, \mathrm{S} 0=\mathrm{H}$ |  |  |  |  |
| VIN pin shunt voltage | VSHUNT | $\mathrm{IVIN}=1 \mathrm{~mA}$ | 19 | 21 | 23 | V |
| VIN pin shunt current | ISHUNT | - | 100 | - | - | mA |
| Output power-good detectionvoltage (Rising) | VOPGH | To preset voltage ratio VVOUT $\geq 3.3 \mathrm{~V}^{[2]}$ | 90 | 94 | 98 | \% |
| Output power-good resetvoltage (Falling) | VOPGL | To preset voltage ratio | 65.5 | 70 | 74.5 | \% |
| Power supply output voltage forinternal circuit | VVB | $\mathrm{VVIN}=6 \mathrm{~V}$ to 20 V | - | $5.0{ }^{[1]}$ | - | V |

[1]: This parameter is not be specified. This should be used as a reference to support designing the circuits.
[2]: Please contact the department in charge if use this output power-good function under the conditions of VVOUT $\leq 2.5 \mathrm{~V}$.

### 6.2 Characteristics of Built-in Bridge Rectification Circuit

Table 5. Characteristics of Built-in Bridge Rectification Circuit
( $\mathrm{Ta}=+25^{\circ} \mathrm{C}$ )

| Parameter | Symbol | Condition | Value |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | Min | Typ | Max |  |
| Forward bias voltage | VF | $\mathrm{IF}=10 \mu \mathrm{~A}$ | 150 | 280 | 450 | mV |
| Forward direction current | IF | - | - | - | 50 | mA |
| Reverse bias leak current | IR | $\mathrm{VR}=18 \mathrm{~V}$ | - | - | 20 | nA |
| Break down voltage | VBREAK | $\mathrm{IR}=1 \mu \mathrm{~A}$ | VSHUNT | 25 | - | V |

### 6.3 AC Characteristics (Input/Output Power-Good)

Table 6. AC Characteristics
( $\mathrm{Ta}=+25^{\circ} \mathrm{C}, \mathrm{VOUT}=3.3 \mathrm{~V}$ )

| Parameter | Symbol | Condition | Value |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | Min | Typ | Max |  |
| Input power-good detection delay time (Rising) | tIPGH | SRVIN $=0.1 \mathrm{~V} / \mathrm{ms}$ | - | 1 | - | ms |
| Input power-good reset delay time (Falling) | tIPGL | SRVIN $=0.1 \mathrm{~V} / \mathrm{ms}$ | - | 1 | - | ms |
| Input power-good undefined time | tIPGX | OPGOOD rising | - | 1 | 3 | ms |
| Output power-good detection delay time (Rising) | tOPGH | $\begin{aligned} & \text { IOUT }=0 \mathrm{~mA}, \\ & \mathrm{~L} 1=22 \mu \mathrm{H}, \\ & \mathrm{C} 2=47 \mu \mathrm{~F}, \end{aligned}$ | - | 1 | - | ms |
| Output power-good reset delay time (Falling) | tOPGL | $\begin{aligned} & \text { IOUT }=1 \mathrm{~mA}, \\ & \mathrm{C} 2=47 \mu \mathrm{~F} \end{aligned}$ | - | 1 | - | ms |

Figure 4. AC characteristics


## 7. Function

### 7.1 Operational Summary

## Bridge Rectifier

The A/C voltage which is input to the AC1_1 and AC1_2 pins or the AC2_1 and AC2_2 pins is all-wave rectified at the bridge rectifier of the low-dissipation diode. The bridge rectifier output is output from the DCOUT1 pin and the DCOUT2 pin. By connecting those outputs to the VIN pin, the electric charge is accumulated to the capacitor and it is used as the energy condenser of the buck converter.

## Power Supply for Internal Circuit

When the VIN pin voltage is 3.5 V or lower, the power supply is supplied from the $\mathrm{V}_{\mathrm{IN}}$ pin to the internal circuit directly. If the VIN pin is over 3.5 V , the internal regulator is activated and the power supply is supplied from the internal regulator to the internal circuit. Therefore, the stable output voltage is maintained in the wide input voltage range 2.6 V to 23 V .

## DC/DC Start-Up/Shut-Down

When the $\mathrm{V}_{\text {IN }}$ pin voltage is over the release voltage VUVLOH for the under voltage lockout protection circuit (UVLO), the converter circuit is enabled and the electric charge is supplied from the input capacitor to the output capacitor. When the $\mathrm{V}^{\mathbb{N}}$ pin voltage is below the UVLO detection voltage VUVLOL, the converter is disabled. The 12 V hysteresis between the release voltage and the detection voltage for UVLO prevents the converter from noise or frequent ON/OFF which is caused by the $\mathrm{V}_{\mathrm{IN}}$ pin voltage-drop during start-up.

## Sleep/Auto Active Control

When the feedback voltage VFB for the converter reaches the determinate voltage, the sleep state to stop the switching operation starts and that can reduce the consumption power from the internal circuit. When the Vout voltage is below the threshold value, the $\mathrm{V}_{\text {OUT }}$ voltage is maintained to the rated value by making the converter active again.

### 7.2 Start-Up/Shut-Down Sequences

Figure 5. Timing Chart


### 7.3 Function Descriptions

Output Voltage Setting and Under Voltage Lockout Protection (UVLO) Function
It is possible to select the output voltage from eight kinds of presets using the S2, S1 and S0 pins.
Also, the under voltage lockout protection circuit is provided to prevent IC's malfunction by the transient state or the instant drop during the VIN pin voltage activation, system destroy and deterioration, and it is set as follows according to the preset voltage. When the VIN pin exceeds the release voltage for the UVLO circuit, the system is recovered.

Table 7. Output Voltage Setting and Under Voltage Lockout Protection (UVLO) Function

| S2 | S1 | S0 | VOUT[V] | Under voltage lockout protection (UVLO) -Typ- |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Detection voltage (Falling) VUVLOL [V] | Release voltage (Rising) VUVLOH [V] |
| L | L | L | 1.5 | 2.8 | 4.0 |
| L | L | H | 1.8 |  |  |
| L | H | L | 2.5 |  |  |
| L | H | H | 3.3 | 4.0 | 5.2 |
| H | L | L | 3.6 |  |  |
| H | L | H | 4.1 | 6.0 | 7.2 |
| H | H | L | 4.5 |  |  |
| H | H | H | 5.0 |  |  |

## Input/output power-good signal output

When the VIN pin input voltage is equal to the release voltage VUVLOH for UVLO or more, the output for the IPGOOD pin is set to the "H" level as the input power-good. When the VIN pin input voltage is equal to the detection voltage VUVLOL for UVLO or less, the output for the IPGOOD pin is reset to the "L" level. The IPGOOD output is enabled only when the following output power-good signal output OPGOOD is "H" level.

The output power-good signal OPGOOD is set to the "H" level when the feedback voltage VFB for the VOUT pin is equal to the detection voltage VOPGH or more. When the feedback voltage VFB is equal to the reset voltage VOPGL or less, the output for the OPGOOD pin is reset to the "L" level.

Table 8. Input Power-Good Signal Output (IPGOOD)

| OPGOOD | UVLO | IPGOOD |
| :---: | :---: | :---: |
| L | Don't care | L |
| $H$ | L | L |
| $H$ | $H$ | $H$ |

Table 9. Output Power-Good Signal Output (OPGOOD)

| VFB | OPGOOD |
| :---: | :---: |
| $\leq$ VOPGL | L |
| $\geq$ VOPGH |  |
| $(\text { VVOUT } \geq 3.3 \mathrm{~V})^{[1]}$ |  |

[1]:Please contact the department in charge if use this output power-good function under the conditions of VVOUT $\leq 2.5 \mathrm{~V}$.

Figure 6. Input/Output Power-Good Signal Output


## Input Over Voltage Protection

If the voltage exceeding VSHUNT (Typ : 21V) is input to the VIN pin, the input level is clamped enabling the over voltage protection circuit. The flowing current is ISHUNT (Min 100mA) during clamp.

## Over Current Protection

If the output current for the LX pin reaches the over current detection level IPEAK, the circuit is protected by controlling the peak value for the inductor current setting the main side FET to the OFF state.

## 8. Typical Application Circuits

Figure 7. Application Circuit For Photovoltaic Energy Harvester


Figure 8. Application circuit for vibration energy harvester


Figure 9. Voltage doubler rectification circuit for vibration harvester


Operation of the double voltage rectifier circuit rectifying an AC input voltage
When the AC1_1 input voltage is positive, the capacitor C4 charges up through the diode DD1, and when the AC1_1 input voltage is negative, the capacitor C5 charges up through the diode DD2. Each capacitor takes on a charge of the positive peak of the AC input. The output voltage at the VIN pin is the series total of $\mathrm{C} 4+\mathrm{C} 5$.

Table 10. Parts list

| Part number | Value | Description |
| :---: | :---: | :---: |
| C 1 | $10 \mu \mathrm{~F}^{[1]}$ | Capacitor |
| C 2 | $47 \mu \mathrm{~F}^{[1]}$ | Capacitor |
| C 3 | $4.7 \mu \mathrm{~F}$ | Capacitor |
| C 4 | $10 \mu \mathrm{~F}^{[1]}$ | Capacitor |
| C5 | $10 \mu \mathrm{~F}^{[1]}$ | Capacitor |
| L 1 | $10 \mu \mathrm{H}$ to $22 \mu \mathrm{H}$ | Inductor |

[1]: Adjust the values according to the source supply ability and the load power.

## 9. Application Notes

## Inductor

The MB39C811 is optimized to work with an inductor in the range of $10 \mu \mathrm{H}$ to $22 \mu \mathrm{H}$. Also, since the peak switching current is up to 400 mA , select an inductor with a DC current rating greater than 400 mA .

Table 11. Manufactures of Recommended Inductors

| Part number | Value | Manufacture |
| :---: | :---: | :---: |
| LPS5030-223ML | $22 \mu \mathrm{H}$ | Coilcraft, Inc. |
| VLF403215MT-220M | $22 \mu \mathrm{H}$ | TDK Corporation |

## Harvester (Photovoltaic Power Generator)

In case of photovoltaic energy harvesting, such as solar or light energy harvesting, use a solar cell with high open-circuit voltage which must be higher than the UVLO release voltage. Electric power obtained from light or solar is increased in proportion to the ambient illuminance.

There are silicone-based solar cells and organic-based solar cells about photovoltaic power generators.Silicone-based solar cells are single crystal silicon solar cell, polycrystalline silicon solar cell, and amorphous silicon solar cell. Organic-based solar cells are dye-sensitized solar cell (DSC), and organic thin film solar cell. Crystal silicon and polycrystalline silicon solar cells have high energy conversion efficiency. Amorphous silicon solar cells are lightweight, flexible, and produced at low cost. Dye-sensitized solar cells are composed by sensitizing dye and electrolytes, and are low-cost solar cell. Organic thin film solar cells are lightweight, flexible, and easily manufactured.

Table 12. Manufactures Of Photovoltaic Harvesters

| Part number/Series name | Type | Manufacture |
| :--- | :--- | :--- |
| BCS4630B9 | Film amorphous silicon solar cells | TDK Corporation |
| Amorton | Amorphous silicon solar cells | Panasonic Corporation |

## Harvester (Vibration Power Generator,Piezoelectric Generator)

Vibration power generators produce AC power by vibration. For AC to DC rectification, the MB39C811 integrates two bridge rectifiers. Electric power obtained from a vibration power generator depends on frequency of vibration and usage of the generator. Although, vibration generators produce high voltage, the shunt circuit protects from higher voltage than 21 V .

There are electromagnetic induction generators and piezoelectric generators about vibration harvesters. The electromagnetic induction generator is consists of coil and magnet. The piezoelectric generators are made from plastics or ceramics. Plastic-based piezoelectric generators made from polyvinylidene fluoride are lightweight, flexible. Ceramic-based piezoelectric generators are made from barium titanate or leas zirconate titanate ceramics.

Table 13. Manufactures of Vibration Harvesters

| Part number | Type | Manufacture |
| :--- | :--- | :--- |
| EH12, EH13, EH15 | Electromagnetic induction | Star Micronics Co., Ltd. |

## Sizing of Input and Output Capacitors

Energy from harvester should be stored on the Cin and Cout to operate the application block. If the size of these capacitors were too big, it would take too much time to charge energy into these capacitors, and the system cannot be operated frequently. On the other hand, if these capacitors were too small, enough energy cannot be stored on these capacitors for the application block. The sizing of the Cin and Cout is important.

Common capacitors are layered ceramic capacitor, electrolytic capacitor, electric double layered capacitor, and so on. Electrostatic capacitance of layered ceramic capacitors is relatively small. However, layered ceramic capacitors are small and have high voltage resistance characteristic. Electrolytic capacitors have high electrostatic capacitance from $\mu \mathrm{F}$ order to mF order. The size of capacitor becomes large in proportion to the size of capacitance. Electric double layered capacitors have high electrostatic capacitance around 0.5 F to 1 F , but have low voltage resistance characteristics around 3 V to 5 V . Be very careful with a voltage resistance characteristic. Also, leak current, equivalent series resistance (ESR), and temperature characteristic are criteria for selecting,

Table 14. Manufactures Of Capacitors

| Part number/Series name | Type, Capacitance | Manufacture |
| :--- | :--- | :--- |
| EDLC351420-501-2F-50 | EDLC, 500 mF |  |
| EDLC082520-500-1F-81 | EDLC, 50 mF |  |
| EDLC041720-050-2F-52 | EDLC, 5 mF | Panasonic Corporation |
| Gold capacitor | EDLC |  |

First of all, apply the following equation and calculate energy consumption for an application from voltage, current, and time during an operation.
$\mathrm{E}_{\text {Appli. }}[\mathrm{J}]=\mathrm{V}_{\text {Appli. }} \times \mathrm{I}_{\text {Appli. }} \times \mathrm{t}_{\text {Appli. }}$
The energy stored on a capacitor is calculated by the following equation.
$\mathrm{E}_{\mathrm{c}}[\mathrm{I}]=\frac{1}{2} \mathrm{CV}^{2}$
Since the energy in a capacitor is proportional to the square of the voltage, it is energetically advantageous for the buck DC/DC converter to make the Cin larger.

An example of an application using the power gating by the OPGOOD signal is shown in the Figure 10. The Cin and the Cout are sized so as to satisfy the following equation. The $\eta$, the efficiency of the MB39C811, is determined from the current of application and the graph shown in Figure 12, Efficiency vs IOUT.

$$
\mathrm{E}_{\text {Appli. }} \leq \mathrm{dE}_{\text {Cin }} \times \eta+\mathrm{dE}_{\text {Cout }}
$$

$\mathrm{dE}_{\mathrm{Cin}}$ and $\mathrm{dE}_{\text {Cout }}$ are the available energies for the application.
$\mathrm{dE}_{\text {Cin }}[I]=\frac{1}{2} \operatorname{Cin}\left(\mathrm{VUVLOH}^{2}-\mathrm{VUVLOL}^{2}\right)$
$\mathrm{dE}_{\text {Cout }}[I]=\frac{1}{2} \operatorname{Cout}\left(\mathrm{VVOUT}^{2}-\operatorname{VOPGL}^{2}\right)$

Figure 10. Application example using the power gating by the OPGOOD signal


Before calculating the initial charging time ( $\mathrm{T}_{\text {Initial }}[\mathrm{s}]$ ), calculate the total energy ( $\mathrm{E}_{\text {Cin }}$ and $\mathrm{E}_{\text {Cout }}$ ) stored on both Cin and Cout.
$\mathrm{E}_{\text {Cout }}[\mathrm{I}]=\frac{1}{2} \mathrm{Cin} \times \mathrm{VUVLOH}^{2}$
$\mathrm{E}_{\text {Cout }}[\mathrm{I}]=\frac{1}{2}$ Cout $\times$ VVOUT $^{2}$
A $P_{\text {Harvester }}[\mathrm{W}]$ is a power generation capability of a harvester. An initial charging time ( $\mathrm{T}_{\text {Initial }}[\mathrm{s}]$ ) is calculated by the following equation.
$\mathrm{T}_{\text {Initial }}=\frac{\mathrm{E}_{\text {Cin }}}{\mathrm{P}_{\text {Harvester }}}+\frac{\mathrm{E}_{\text {Cout }}}{\mathrm{P}_{\text {Harvester }} \times \eta}$
A repeat charging time ( $T_{\text {Repeat }}[s]$ ) is calculated by the following equation. The $T_{\text {Repeat }}[s]$ become shorter than the $\mathrm{T}_{\text {Initial }}[\mathrm{s}]$.
$\mathrm{T}_{\text {Repeat }}=\frac{\mathrm{dE}_{\text {Cin }}}{\mathrm{P}_{\text {Harvester }}}+\frac{\mathrm{dE}_{\text {Cout }}}{\mathrm{P}_{\text {Harvester }} \times \eta}$
Additionally, waiting for a period of time after the OPGOOD signal goes high can store more energy on the capacitor Cin Figure 11.
$\mathrm{dE}_{\text {Cout }}[\mathrm{J}]=\frac{1}{2} \mathrm{Cin}\left(\mathrm{V}_{\text {OpenCircuitVoltage }}^{2}-\mathrm{VUVLOL}^{2}\right)$

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Figure 11. Waiting for a Period of Time after the OPGOOD Signal goes High


For more information about the energy calculation, refer to the APPLICATION NOTE, Energy Calculation For Energy Harvesting.

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## 10. Typical Characteristics

Figure 12. Typical characteristics of DC/DC Converter




Figure 13. Typical Characteristics of Bridge Rectifier


Figure 14. DC/DC Converter Sudden Load Change


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Figure 15. Switching Waveforms of DC/DC Converter





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## 11. Layout for Printed Circuit Board

## Note the points listed below in layout design

■ Place the switching parts ${ }^{[1]}$ on top layer, and avoid connecting each other through through-holes.

- Make the through-holes connecting the ground plane close to the GND pins of the switching parts ${ }^{[1]}$
- Be very careful about the current loop consisting of the input capacitor CVIN, the VIN pin of IC, and the PGND pin. Place and connect these parts as close as possible to make the current loop small.

■ The output capacitor CVOUT and the inductor L are placed adjacent to each other.

- Place the bypass capacitor CVB close to VB pin, and make the through-holes connecting the ground plane close to the GND pin of the bypass capacitor CVB.

■ Draw the feedback wiring pattern from the VOUT pin to the output capacitor CVOUT pin. The wiring connected to the VOUT pin is very sensitive to noise so that the wiring should keep away from the switching parts ${ }^{[1]}$. Especially, be very careful about the leaked magnetic flux from the inductor $L$, even the back side of the inductor $L$.
[1]: Switching parts: IC (MB39C811), Input capacitor (CVIN), Inductor (L), Output capacitor (CVOUT). Refer to Figure 2.

Figure 16. Example of a Layout Design


